

Notice of References Cited

Application/Control No.

09/661,057

Applicant(s)/Patent Under
Reexamination
OHTANI ET AL.

Examiner

Tarifur R Chowdhury

Art Unit

2871

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U.S. PATENT DOCUMENTS

U.S. PATENT DOCUMENTS					
*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-5,687,465	11-1997	Hinata et al.	156/286
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
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	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS		
		Classification

FOREIGN PATENT DOCUMENTS

	M	US-	FOREIGN PATENT DOCUMENTS			
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	N	WO 97/39380	10-1997	PCT	KHAN et al	
	O					
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NON-PATENT DOCUMENTS				Volume Pertinent Pages)		

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	U	""HDBU (High Density Build Up) Organic Package Technology that is first in the industry to employ "Laser Via" method", Kyocera Corporation, February 15, 1999.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.